

JEDEC PUBLICATION

PartModel Generated ECAD - Models Guidelines for Electronic-Device Packages – XML Requirements

JEP30-M100

February 2025

JEDEC SOLID STATE TECHNOLOGY ASSOCIATION



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PartModel Generated ECAD Models Guidelines for Electronic-Device Packages – XML Requirements

(From JEDEC Board Ballots JCB-24-53, formulated under the cognizance of the JC-11 Committee on Mechanical Standardization.)

1 Scope

The JEP30 document establishes the requirements for exchanging part data between part manufacturers and their customers for electrical and electronic products. The JEP30 documents are part of a series to describe XML data exchange structure and hierarchy. The JEP30 document series will detail data exchange between companies for design at the next level, analysis, and interconnection. The parent JEP30 document specifically focuses on the parental structure, under which several sub-sections are listed, such as electrical, physical, thermal, supply chain, assembly process classification, design kit, and environment including material declaration. This document adds a new section called the generated ECAD model section to the JEP30 PartModel XML Schema series.

1.1 Purpose

This standard is intended to benefit part manufacturers, ecad model generators and their customers by providing consistency and efficiency to the transfer of standardized ECAD models from model generators to customers. It establishes standard electronic data exchange formats that will facilitate and improve data transfer along the entire global supply chain, at every stage in the product life cycle. A key aspect therefore is the structure of the content that is contained in this format, which the committee believes should be based on the following two principals:

- 1) Data that is required to be consumed by software tools, and
- 2) Data that is not required to be consumed by software tools but is provided for informational purpose.

This standard specifically covers data applicable to the [*GeneratedECAD-Models*](#) that is required to support the design, fabrication and consumption modelling of the device.

2 Applicable Documents

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

2.1 JEDEC (www.jedec.org)

JEP30, *PartModel Guidelines for Electronic-Device Packages – XML Requirements*

JEP30-A100, PartModel Assembly Process Classification Guidelines for Electronic-Device Packages – XML Requirements

JEP30-E100, *PartModel Electrical Guidelines for Electronic-Device Packages – XML Requirements*

JEP30-P100, PartModel Package Guidelines for Electronic-Device Packages – XML Requirements

JEP30-T100, PartModel Thermal Guidelines for Electronic-Device Packages – XML Requirements

2.1.1 JEDEC PartModel Schema and Sub-Schemas

JEP30-10, PartModel Schema

JEP30-A101, PartModel Assembly Process Classification Schema

JEP30-E101, PartModel Electrical Schema

JEP30-P101, PartModel Package Schema

JEP30-S101, PartModel Supply Chain Schema

JEP30-T101, PartModel Thermal Schema

JEP30-K101, PartModel Design Kit Schema

JEP30-M101, PartModel Generated ECAD – Models Schema

JEP30-D10, *PartModel Schema Types Dictionary* (Required to support the PartModel Schema and each of its sectional sub-schemas.)

3 Requirements

The following terms and definitions are applicable to this XML Schema.

3.1 Terms and Definitions

All definitions and terms associated with the generated ECAD Model data are defined in the relevant standards that govern the definition of those parameters, as listed in the applicable documents section. The Design Kit details of the part are defined in the [GeneratedECAD-ModelsSection](#) of the XML Schema.

All common Terms and Definitions that are used by more than one sectional sub-schema, such as any of the Assembly Process Classification, Electrical, Environmental, Package, Supply Chain, Thermal, Design Kits, or Generated ECAD Models are defined in the “JEP30-D10 PartModel Schema Types Library”.

All other definitions and terms necessary to define the schema, are defined by this document.

PartModel: A PartModel is a data representation described in an XML file that conforms to the rules and structure of the PartModel XML Schema.

NOTE 1 Companies who use the PartModel XML Files and claim compliance to JEDEC, must ensure that their PartModel XML file conforms to the specific released version of the PartModel XML Schema released by JEDEC.

NOTE 2 Section 4 will define the outline of the structure of the Generated ECAD Models XML Schema. Specific components of the XML Schema and their hierarchy are specifically controlled by the JC-11 Standards Committee who retain the expertise for these structures.

NOTE 3 The [GeneratedECAD-ModelsSection](#) of the schema forms part of the PartModel XML Schema and is not intended to act as a standalone schema. In addition, there is a “PartModel Schema Types Library” XML Schema, which is a common set of xml structures shared across the PartModel XML Schema and all of its sub-section schemas.

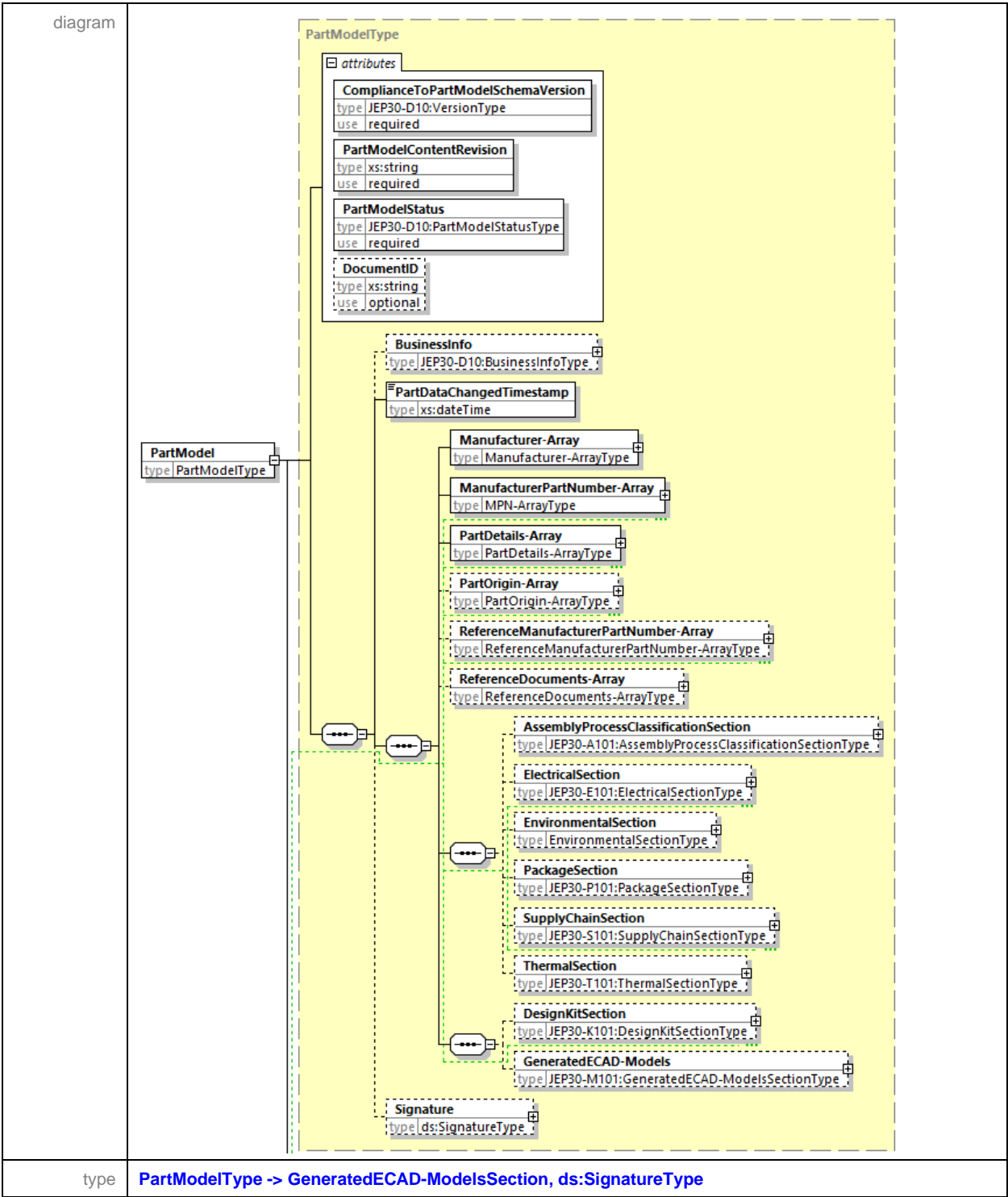
3.2 XML Schema Key Terms and Definitions

Reference the JEP30 publication for details of the "XML Schema Key Terms and Definitions".

4 PartModel Schema Definition

The following section describes the XML Schema structure.

4.1 PartModel – Generated ECAD - Models Section



4.1 PartModel – Generated ECAD - Models Section (cont'd)

The [PartModelType](#) belongs to the “PartModel XML Schema”. The [GeneratedECAD-ModelsSection](#) belongs to the “PartModel Generated ECAD Models XML Schema”. The primary purpose of the PartModel Schema is to provide the structure for identifying unique parts (Manufacturer and MPN), and the structure to include the sub schemas which define the part details, as outline in the JEP30 - PartModel Guidelines for Electronic-Device Packages – XML Requirements.

This document covers the [GeneratedECAD-ModelsSection](#), which is referenced from its parent’s structure, the [PartModel](#). The contents under the [GeneratedECAD-ModelsSection](#) are

1. Tied to the Manufacturer’s name and Manufacturer’s part number if the ECAD model is applicable to a part or a chiplet, or
2. Tied to a Standards Body and a Standards Model Identifier, if the ECAD models represents a standard set of Interfaces or Functions or Package Models as defined by a specific Standards Body.

All releases of the [GeneratedECAD-ModelsSection](#) sub-schema must be under the umbrella of the PartModel Schema to ensure that the PartModel schema is referencing the correct version of the Generated ECAD Models sub-schema. In addition, this will enable the Generated ECAD Models sub-schemas to connect to the identity structure as defined in the parent schema JEP30.

The [ComplianceToPartModelSchemaVersion](#) indicates the version of the Schema to which the XML file is to be validated against. All new releases to this document or XML Schema is governed by the rules outlined in JEP30, and must be released in sync with the PartModel.

“Each time that a Sub-schema gets updated, then the PartModel version also gets updated in order to release that Sub-schema under the umbrella of the PartModel. This is because the PartModel must now reference the new version of sub-schema, since all subschemas have their own version number. The parent schema includes them by referring to a precise version, so a version bump in the subschema requires a version bump in the parent only at the time of release of the Parent.”

The [PartModelContentRevision](#) indicates the revision of the data for the Part that is submitted in the XML file. This enables the Component Manufacturer or the PartModel generator to provide a new XML file for a Part each time they wish to upgrade a new set of data for a part, in any of the sub-sections such as this [GeneratedECAD-ModelsSection](#).

4.2 Manufacturer Part Number-Array

path	PartModel/ManufacturerPartNumber-Array.
diagram	<p>The diagram illustrates the XSD structure for the ManufacturerPartNumber-Array. It is defined as an MPN-ArrayType containing a ManufacturerPartNumbers element (1..∞) of type ManufacturerPartNumbersType. This type contains several optional elements (0..∞): ID (xs:string), PartNumberSeries (PartNumberType), OrderablePartNumber (OrderablePartNumberType), FuturePart (FuturePartType), StandardsIdentifier (StandardsIdentifierType), ProcessTechnologyIdentifier (ProcessTechnologyIdentifierType), ManufacturerID (xs:string), ManufacturerSignatureDigest (JEP30-D10:SignatureDigestLinkType), and ManufacturerPartNumbersIdentitySignature (ds:SignatureType).</p>
type	MPN-ArrayType , ManufacturerPartNumbersType , PartNumberType , OrderablePartNumberType , FuturePartType , StandardsIdentifierType , ProcessTechnologyIdentifierType , JEP30-D10:SignatureDigestLinkType , ds:SignatureType .

The [ManufacturerPartNumber-Array/ManufacturerPartNumbers](#) provides the definition of the part number, model, or a specific Standard, so that it can be connected to the technical specification details in the [GeneratedECAD-ModelsSection](#) via the [PartDetails-Array](#) section.

4.3 Linking the Manufacturing Part Number to a specific ECAD Model Data set

The linking of the Parts, or Standards to its technical data is done via the [PartDetails-Array](#) section as outline in the JEP30 - PartModel Guidelines for Electronic-Device Packages – XML Requirements. This consists of two sections called [PartsSelection-Array](#) and [Association-Array](#) which defines the relationship between identifying the specific set of parts, standard interfaces, functions or packages and how they are associated with the ECAD Model content. Reference the JEP30 parent document for more details on this association.

4.3 Linking the Manufacturing Part Number to a specific Design Kit Data set (cont'd)

path	PartModel/PartDetails-Array/PartDetails/Association-Array/Association/GeneratedECAD-Models-Array
diagram at the Association level	<p>The diagram shows a class GeneratedECAD-Models-Array (type <code>GeneratedECAD-ModelsAssociation-ArrayType</code>) associated with a class GeneratedECAD-ModelsAssociation-ArrayType. The latter contains three sub-associations: Footprint (type <code>FootprintAssociationType</code>), Symbol (type <code>SymbolAssociationType</code>), and TerminalName-to-NumberMapping (type <code>TerminalName-to-NumberMappingAssociationType</code>). Each sub-association has a multiplicity of <code>0..∞</code>.</p>
type	GeneratedECAD-ModelsAssociation-ArrayType, FootprintAssociationType, SymbolAssociationType, TerminalName-to-NumberMappingAssociationType.
path	PartModel/GeneratedECAD-ModelsSection
diagram at the Generated ECAD - Models Section level	<p>The diagram shows a class GeneratedECAD-ModelsSection (type <code>GeneratedECAD-ModelsSectionType</code>) associated with a class GeneratedECAD-ModelsSectionType. The latter contains four sub-associations: attributes (type <code>GeneratedFootprint-ArrayType</code>), constraints (type <code>GeneratedSymbol-ArrayType</code>), Footprint-Array (type <code>GeneratedFootprint-ArrayType</code>), Symbol-Array (type <code>GeneratedSymbol-ArrayType</code>), TerminalName-to-NumberMapping-Array (type <code>TerminalName-to-NumberMapping-ArrayType</code>), and GeneratedECAD-ModelOrigin-Array (type <code>GeneratedECAD-ModelOrigin-ArrayType</code>). Each sub-association has a multiplicity of <code>0..∞</code>.</p>
type	JEP30-M101:GeneratedECAD-ModelsSectionType, GeneratedFootprint-ArrayType, GeneratedSymbol-ArrayType, TerminalName-to-NumberMapping-ArrayType, GeneratedECAD-ModelOrigin-ArrayType.

4.3.1 Linking the Manufacturing Part Number to Footprint ECAD Model

path	PartModel/PartDetails-Array/PartDetails/Association-Array/Association/GeneratedECAD-Models-Array/Footprint
diagram at the Footprint Generated ECAD Models Association level	<p>The diagram illustrates the FootprintAssociationType structure. It contains a Footprint element (type FootprintAssociationType, cardinality 0..∞) and a FootprintID element (type xs:string). A red circle labeled 'A' points to the FootprintID element.</p>
type	FootprintAssociationType , JEP30-D10:SignatureDigestLinkType .
path	PartModel/GeneratedECAD-ModelsSection/Footprint-Array
diagram at the Footprint Generated ECAD Models level.	<p>The diagram illustrates the GeneratedFootprint-ArrayType structure. It contains a Footprint-Array element (type GeneratedFootprint-ArrayType, cardinality 1..∞) and a Footprint element (type GeneratedFootprintType, cardinality 1..∞). The Footprint element contains the following sub-elements: ID (type xs:string), FootprintName (type xs:string), FootprintExtendedName (type xs:string), Polarity (type JEP30-D10:EmptyType), InterconnectTechnology-Array (type JEP30-D10:InterconnectTechnology-ArrayType), PadOrHoleShape-Array (type JEP30-D10:PadOrHole-ArrayType), ThermalRelief-Array (type JEP30-D10:ThermalRelief-ArrayType), AssemblyOutlineLayer (type JEP30-D10:AssemblyOutlineLayerType), ConductiveArea-Array (type JEP30-D10:ConductiveArea-ArrayType), PlacementOutline (type JEP30-D10:PlacementOutlineType), Keep-inLayer-Array (type JEP30-D10:Keep-inLayer-ArrayType), KeepoutRegion-Array (type JEP30-D10:KeepoutRegion-ArrayType), SoldermaskLayer-Array (type JEP30-D10:SoldermaskLayer-ArrayType), PastemaskLayer-Array (type JEP30-D10:PastemaskLayer-ArrayType), ModelOrigin (type ModelOriginType), and FootprintSignature (type ds:SignatureType). A red circle labeled 'A' points to the ID element.</p>
type	GeneratedFootprint-ArrayType , GeneratedFootprintType , JEP30-D10:EmptyType , JEP30-D10:InterconnectTechnology-ArrayType , JEP30-D10:PadOrHole-ArrayType , JEP30-D10:ThermalRelief-ArrayType , JEP30-D10:AssemblyOutlineLayerType , JEP30-D10:ConductiveArea-ArrayType , JEP30-D10:PlacementOutlineType , JEP30-D10:Keep-inLayer-ArrayType , JEP30-D10:KeepoutRegion-ArrayType , JEP30-D10:SoldermaskLayer-ArrayType , JEP30-D10:PastemaskLayer-ArrayType , ModelOriginType , ds:SignatureType .

4.3.1. Linking the Manufacturing Part Number to Footprint ECAD Model (cont'd)

The [FootprintID](#) references the [Footprint/ID](#) under the GeneratedECAD-ModelsSection/Footprint-Array. This is enforced by the key named as [GeneratedFootprintModelKey](#) that is assigned to the [Footprint/ID](#) element, which is referenced by the [FootprintID](#) which has a KeyRef that refers to the [JEP30-M101:GeneratedFootprintModelKey](#).

4.3.2 Linking the Manufacturing Part Number to Symbol ECAD Model

path	PartModel/PartDetails-Array/PartDetails/Association-Array/Association/GeneratedECAD-Models-Array/Symbol
diagram at the Symbol Generated ECAD Models Association level	
type	SymbolAssociationType , JEP30-D10:SignatureDigestLinkType .
path	PartModel/GeneratedECAD-ModelsSection/Symbol-Array
diagram at the Symbol Generated ECAD Models level.	
type	GeneratedSymbol-ArrayType , GeneratedSymbolType , JEP30-D10:SymbolGraphics-ArrayType , ModelOriginType , ds:SignatureType .

The [SymbolID](#) references the [Symbol/ID](#) under the GeneratedECAD-ModelsSection/Symbol-Array. This is enforced by the key named as [GeneratedSymbolModelKey](#) that is assigned to the [Symbol/ID](#) element, which is referenced by the [SymbolID](#) which has a KeyRef that refers to the [JEP30-M101:GeneratedSymbolModelKey](#).

4.3.3 Linking the Manufacturing Part Number to Material Design Kit

path	PartModel/PartDetails-Array/PartDetails/Association-Array/Association/GeneratedECAD-Models-Array/TerminalName-to-NumberMapping
diagram at the Material Design Kit Association level	
type	TerminalName-to-NumberMappingAssociationType , JEP30-D10:SignatureDigestLinkType .
path	PartModel/GeneratedECAD-ModelsSection/TerminalName-to-NumberMapping-Array
diagram at the Material Design Kit level.	
type	TerminalName-to-NumberMapping-ArrayType , TerminalName-to-NumberMappingType , Map-ArrayType , ModelOriginType , ds:SignatureType .

The [TerminalName-to-NumberMappingID](#) references the [TerminalName-to-NumberMapping/ID](#) under the [GeneratedECAD-ModelsSection/TerminalName-to-NumberMappingID-Array](#). This is enforced by the key named as [GeneratedTerminalName-to-NumberMappingKey](#) that is assigned to the [TerminalName-to-NumberMapping/ID](#) element, which is referenced by the [TerminalName-to-NumberMappingID](#) which has a KeyRef that refers to the [JEP30-M101:GeneratedTerminalName-to-NumberMappingKey](#).

5 **Generated ECAD – Models Section**

path	PartModel/GeneratedECAD-ModelsSection
diagram	<p>The diagram illustrates the structure of the GeneratedECAD-ModelsSectionType. It features a class box for GeneratedECAD-ModelsSection with a type attribute pointing to GeneratedECAD-ModelsSectionType. This points to a large dashed box representing the GeneratedECAD-ModelsSectionType, which contains an attributes compartment with four array types: Footprint-Array (GeneratedFootprint-ArrayType), Symbol-Array (GeneratedSymbol-ArrayType), TerminalName-to-NumberMapping-Array (TerminalName-to-NumberMapping-ArrayType), and GeneratedECAD-ModelOrigin-Array (GeneratedECAD-ModelOrigin-ArrayType). A constraints compartment is also shown at the bottom.</p>
type	JEP30-M101:GeneratedECAD-ModelsSectionType, GeneratedFootprint-ArrayType, GeneratedSymbol-ArrayType, TerminalName-to-NumberMapping-ArrayType, GeneratedECAD-ModelOrigin-ArrayType.

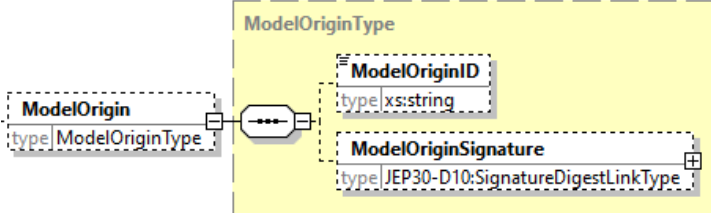
The *GeneratedECAD-ModelsSection* consists of 4 sections as shown above in the diagram. Each of these sections are described in further detail in the sub-sections below.

5.1 Footprint - Array

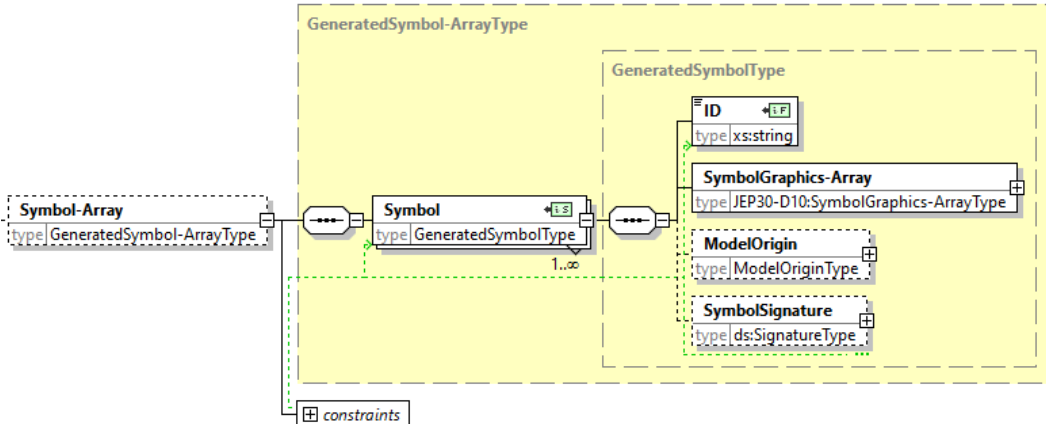
path	PartModel/GeneratedECAD-ModelsSection/Footprint-Array
diagram	<p>The diagram illustrates the XSD structure for the Footprint-Array. It is composed of the following elements and types:</p> <ul style="list-style-type: none"> Footprint-Array (type <code>GeneratedFootprint-ArrayType</code>): The root element, which contains one or more Footprint elements. Footprint (type <code>GeneratedFootprintType</code>): The element representing a single footprint. It includes: <ul style="list-style-type: none"> ID (type <code>xs:string</code>): A unique identifier for the footprint. FootprintName (type <code>xs:string</code>): The name of the footprint. FootprintExtendedName (type <code>xs:string</code>): An extended name for the footprint. Polarity (type <code>JEP30-D10:EmptyType</code>): A field for polarity information. InterconnectTechnology-Array (type <code>JEP30-D10:InterconnectTechnology-ArrayType</code>): An array of interconnect technology details. PadOrHoleShape-Array (type <code>JEP30-D10:PadOrHole-ArrayType</code>): An array of pad or hole shapes. ThermalRelief-Array (type <code>JEP30-D10:ThermalRelief-ArrayType</code>): An array of thermal relief details. AssemblyOutlineLayer (type <code>JEP30-D10:AssemblyOutlineLayerType</code>): The assembly outline layer. ConductiveArea-Array (type <code>JEP30-D10:ConductiveArea-ArrayType</code>): An array of conductive areas. PlacementOutline (type <code>JEP30-D10:PlacementOutlineType</code>): The placement outline. Keep-inLayer-Array (type <code>JEP30-D10:Keep-inLayer-ArrayType</code>): An array of keep-in layer details. KeepoutRegion-Array (type <code>JEP30-D10:KeepoutRegion-ArrayType</code>): An array of keepout regions. SoldermaskLayer-Array (type <code>JEP30-D10:SoldermaskLayer-ArrayType</code>): An array of soldermask layers. PastemaskLayer-Array (type <code>JEP30-D10:PastemaskLayer-ArrayType</code>): An array of pastemask layers. ModelOrigin (type <code>ModelOriginType</code>): The model origin. FootprintSignature (type <code>ds:SignatureType</code>): A digital signature for the footprint. constraints: A box indicating that the Footprint element is required (indicated by a solid line) and that the Footprint-Array contains one or more (<code>1..∞</code>) such elements.
type	GeneratedFootprint-ArrayType, GeneratedFootprintType, JEP30-D10:EmptyType, JEP30-D10:InterconnectTechnology-ArrayType, JEP30-D10:PadOrHole-ArrayType, JEP30-D10:ThermalRelief-ArrayType, JEP30-D10:AssemblyOutlineLayerType, JEP30-D10:ConductiveArea-ArrayType, JEP30-D10:PlacementOutlineType, JEP30-D10:Keep-inLayer-ArrayType, JEP30-D10:KeepoutRegion-ArrayType, JEP30-D10:SoldermaskLayer-ArrayType, JEP30-D10:PastemaskLayer-ArrayType, ModelOriginType, ds:SignatureType.

The **Footprint-Array** follows the same structure as the Recommended Footprint Array that is specified in the JEP30-P100 PartModel Package Guidelines for Electronic-Device Packages – XML Requirements. Reference that document for the details of each sub-section.

5.1.1 Model Origin

path	PartModel/DesignKitSection/PackageAssemblyDesignKit-Array/PackageAssemblyDesignKit/RuleCondition-Array
diagram	 <p>The diagram shows a dashed box labeled ModelOriginType. Inside, there is a ModelOrigin element with a dashed border and the text <i>type ModelOriginType</i>. To its right is a solid box containing two elements: ModelOriginID with <i>type xs:string</i>, and ModelOriginSignature with <i>type JEP30-D10:SignatureDigestLinkType</i>. A dashed line connects the ModelOrigin element to the ModelOriginID element. A small box with a plus sign and the word constraints is located at the bottom right of the ModelOriginType box.</p>
type	ModelOriginType , JEP30-D10:SignatureDigestLinkType .

5.2 Symbol - Array

path	PartModel/GeneratedECAD-ModelsSection/Symbol-Array
diagram	 <p>The diagram shows a dashed box labeled GeneratedSymbol-ArrayType. Inside, there is a Symbol-Array element with a dashed border and the text <i>type GeneratedSymbol-ArrayType</i>. To its right is a solid box containing a Symbol element with a dashed border and the text <i>type GeneratedSymbolType</i>. The Symbol element has a multiplicity of 1..∞. To the right of the Symbol element is another dashed box labeled GeneratedSymbolType. Inside this box, there is an ID element with <i>type xs:string</i> and a multiplicity of 1..1. Below the ID element is a SymbolGraphics-Array element with <i>type JEP30-D10:SymbolGraphics-ArrayType</i> and a multiplicity of 1..∞. Below the SymbolGraphics-Array element are two more elements: ModelOrigin with <i>type ModelOriginType</i> and SymbolSignature with <i>type ds:SignatureType</i>. A dashed line connects the Symbol element to the GeneratedSymbolType box. A small box with a plus sign and the word constraints is located at the bottom left of the GeneratedSymbol-ArrayType box.</p>
type	GeneratedSymbol-ArrayType , GeneratedSymbolType , JEP30-D10:SymbolGraphics-ArrayType , ModelOriginType , ds:SignatureType .

The [Symbol-Array](#) follows the same structure as the Symbol-Array that is specified in the JEP30-E100 PartModel Electrical Guidelines for Electronic-Device Packages – XML Requirements. Reference that document for the details of each sub-section.

5.3 Terminal Name – to – Number Mapping - Array

path	PartModel/GeneratedECAD-ModelsSection/TerminalName-to-NumberMapping-Array
diagram	
type	TerminalName-to-NumberMapping-ArrayType , TerminalName-to-NumberMappingType , Map-ArrayType , ModelOriginType , ds:SignatureType .

5.3.1 Map - Array

path	PartModel/DesignKitSection/PackageAssemblyDesignKit-Array/PackageAssemblyDesignKit/DesignClassification-Array
diagram	
type	Map-ArrayType , MapType .

5.4 Generated ECAD - Model Origin - Array

path	PartModel/GeneratedECAD-ModelsSection/GeneratedECAD-ModelOrigin-Array
diagram	
type	GeneratedECAD-ModelOrigin-ArrayType, GeneratedECAD-ModelOriginType, JEP30-D10:OriginLocation-ArrayType, JEP30-D10:ContactType, JEP30-D10:ContactType, ds:SignatureType, JEP30-D10:CompanyLocations-ArrayType

5.4.1 Origin Location - Array

path	PartModel/GeneratedECAD-ModelsSection/GeneratedECAD-ModelOrigin-Array/GeneratedECAD-ModelOrigin/OriginLocation-Array
diagram	
type	JEP30-D10:OriginLocation-ArrayType, OriginLocationType, ExternalOriginLocationType, SignatureDigestLinkType.

The *InternalCompanyLocationID*, *ExternalCompanyLegalEntityLocationID*, and the *ExternalCompanyProcessOriginLocationID* connects to the company location details under the *CompanyLocations-Array/CompanyLocation/ID*.

5.4.1. Origin Location - Array (cont'd)

It is recommended that the *GeneratedECAD-ModelOrigin* details contain the *Contact* and *Authorizer* details and that this structure is digitally signed off via the *GeneratedECAD-ModelOriginSignature*. This will help to build trust in the supply chain for the part.

5.4.2 Company Location - Array

path	PartModel/GeneratedECAD-ModelsSection/GeneratedECAD-ModelOrigin-Array/CompanyLocations-Array
diagram	<p>The diagram illustrates the XSD structure for the CompanyLocations-Array. It is an array of CompanyLocation elements, each of type CompanyLocationType. The CompanyLocationType contains the following fields:</p> <ul style="list-style-type: none"> ID: type <code>xs:string</code>, required (indicated by a red '1' in a box). Name: type <code>xs:string</code>, required (indicated by a red '1' in a box). SiteLocationIdentity: type <code>SiteLocationIdentityType</code>, required (indicated by a red '1' in a box). Authorizer: type <code>JEP30-D10:ContactType</code>, optional (indicated by a red '0' in a box). Contact: type <code>JEP30-D10:ContactType</code>, optional (indicated by a red '0' in a box). CompanyLocationSignature: type <code>ds:SignatureType</code>, optional (indicated by a red '0' in a box). <p>The CompanyLocations-Array is of type <code>CompanyLocations-ArrayType</code>. A constraints box is also present at the bottom of the diagram.</p>
type	CompanyLocations-ArrayType , CompanyLocationType , SiteLocationIdentityType , JEP30-D10: ContactType , ds:SignatureType .

Annex A (informative) Differences between JEP30-M100 and its predecessors

This table briefly describes most of the changes made to entries that appear in this standard, JEP30-M100, compared to its predecessor; Punctuation changes may or may not be included.

Initial Issue:	Date: February 2025	Item Number: 11.2-1073
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Change Record History

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Standard Improvement Form**JEDEC Standard No. JEP30-M100**

The purpose of this form is to provide the Technical Committees of JEDEC with input from the industry regarding usage of the subject standard. Individuals or companies are invited to submit comments to JEDEC. All comments will be collected and dispersed to the appropriate committee(s).

If you can provide input, please complete this form and return to:

JEDEC
Attn: Publications Department
3103 10th Street North
Suite 240S
Arlington, VA 22201

Email: angies@jedec.org

1. I recommend changes to the following:

☐ Requirement, clause number _____

☐ Test method number _____ Clause number _____

The referenced clause number has proven to be:

☐ Unclear ☐ Too Rigid ☐ In Error

☐ Other _____

2. Recommendations for correction:

3. Other suggestions for document improvement:

Submitted by

Name: _____

Company: _____

Address: _____

City/State/Zip: _____

Phone: _____

E-mail: _____

Date _____

